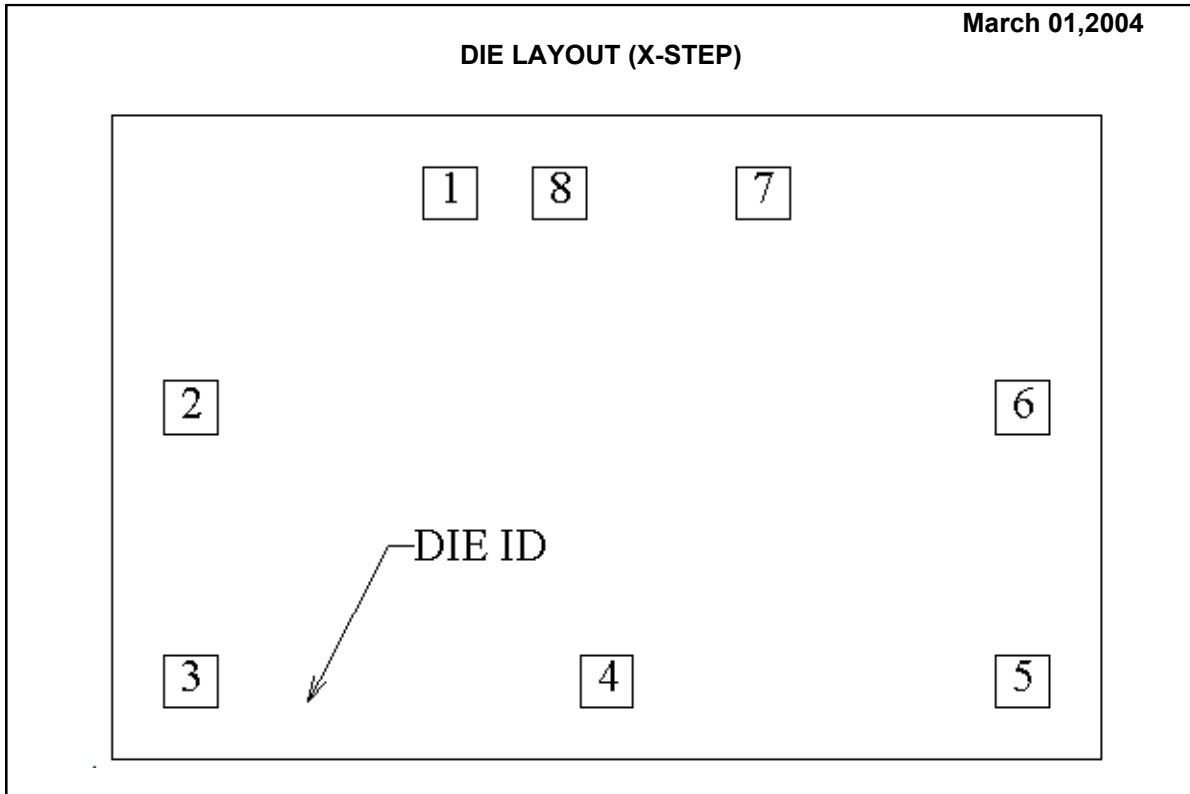


**LM1558 MD8 MW8  
DUAL OPERATIONAL AMPLIFIER**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	1558	Bond Pad Opening Size (min)	86µm x 86µm
Die Step	X	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VAPOX
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1600µm x 1041µm 63.0mils x 41.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	177µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (X -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
OUTPUT A	1	-254	394	86	x	86
INPUT A-	2	-673	48	86	x	86
INPUT A+	3	-673	-394	86	x	86
V-	4	0	-394	86	x	86
INPUT B+	5	673	-394	86	x	86
INPUT B-	6	673	48	86	x	86
OUTPUT B	7	254	394	86	x	86
V+	8	-76	394	86	x	86

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